QIT Press - International Journal of Computer Science (QITP-IJCS)
Journal ID: 0001-5732
Volume 3, Issue 1, January-December 2023, pp. 7-12

Benchmarking Classical and Deep Learning Approaches for Defect Detection in High-Resolution Wafer Inspection Imaging

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Published on: 20th March 2023

Citation: Tyrone R. (2023). Benchmarking Classical and Deep Learning Approaches for Defect Detection in High-Resolution Wafer Inspection Imaging. QIT Press - International Journal of Computer Science (QITP-IJCS), 3(1), 7–12.

Full Text: https://qitpress.com/articles/QITP-IJCS/VOLUME_3_ISSUE_1/QITP-IJCS_3_01_002.pdf

Abstract

High-resolution wafer inspection is a critical step in semiconductor manufacturing, directly impacting yield and reliability. This paper benchmarks classical image processing techniques against recent deep learning models for defect detection in wafer images. We compare accuracy, computational performance, and robustness across various defect types using a standardized dataset. Results reveal that while deep learning offers superior accuracy, classical methods still excel in specific, low-variance detection scenarios. The study highlights the trade-offs involved in real-time inspection systems and offers guidance on model selection based on practical deployment requirements.

Keywords: Wafer inspection · Defect detection · Deep learning · Image processing · Semiconductor manufacturing · Convolutional neural networks

1. Introduction

The semiconductor industry is driven by a relentless demand for smaller, faster, and more reliable chips. As the complexity of integrated circuits (ICs) increases, the detection of minute defects in semiconductor wafers becomes crucial. Defect detection in high-resolution wafer inspection images is not only essential for quality control but also for reducing production losses and improving process yield.

Traditionally, wafer inspection systems relied heavily on classical image processing algorithms, such as morphological operations, edge detection, and statistical pattern recognition. However, with the advent of deep learning—particularly convolutional neural networks (CNNs)—a paradigm shift has occurred in automated visual inspection. Despite their promise, deep learning models require

significant computational resources and large annotated datasets, raising concerns for deployment in real-time environments. This study aims to benchmark both classical and deep learning approaches, evaluating their trade-offs in performance, accuracy, and feasibility for real-world deployment.

2 Classical Defect Detection Methods

Classical defect detection methods have long served as the foundation of automated wafer inspection, relying primarily on rule-based and statistical techniques for visual anomaly identification. These methods typically involve sequential image processing steps such as grayscale conversion, background subtraction, noise filtering, and the application of edge detection or morphological transformations. Common algorithms used include thresholding combined with morphological operators, Canny edge detection, and Gabor filters, each offering specific advantages depending on the defect type and image characteristics.

One of the strengths of classical methods lies in their simplicity and low computational demands, making them well-suited for real-time or resource-constrained environments. For instance, thresholding followed by morphological operations offers fast processing speeds and decent accuracy when detecting high-contrast defects. Canny edge detection, although more computationally intensive, enhances the identification of scratches or line-based anomalies. Gabor filters, which are sensitive to texture and orientation, have been used effectively to capture fine structural patterns. Table 1 summarizes the comparative performance of these classical methods in terms of detection accuracy and processing time, illustrating their strengths in speed but also their limitations in adaptability and sensitivity to noise or variable imaging conditions.

Table 1: Performance metrics of classical image processing methods on high-resolution wafer dataset.

Method	**Detection Accuracy (%)**	**Processing Time (ms/img)**
Threshold + Morphology	72.3	12.4
Canny Edge Detection	68.9	15.8
Gabor Filters	76.1	22.1

3 Deep Learning for Wafer Inspection

Deep learning has enabled substantial improvements in image recognition tasks, including defect detection. CNNs, in particular, have shown state-of-the-art results due to their ability to learn hierarchical features directly from data. Models such as U-Net and ResNet have been adapted for pixel-wise segmentation and classification of wafer defects.

Unlike classical methods, deep learning approaches do not require manual feature design. However, they depend heavily on large labeled datasets and high-performance GPUs for training and inference. This makes them less suitable for applications with strict latency requirements unless optimized using edge AI or pruning techniques.

Table 2: Deep learning model performance on wafer defect dataset.

Model	Detection Accuracy (%)	Inference Time (ms/img)
U-Net	94.5	45.2
ResNet-50	92.8	38.7
YOLOv3	89.6	33.4

4 Comparative Analysis

The comparative evaluation of classical image processing methods and deep learning models reveals significant trade-offs in terms of detection performance, computational efficiency, and deployment feasibility. Classical approaches such as thresholding, Canny edge detection, and Gabor filters continue to offer viable solutions in controlled environments where defect patterns are relatively uniform and well-defined. These methods demonstrated lower processing times (typically under 25 ms per image) and were particularly effective for detecting prominent structural anomalies. However, their performance declines markedly in scenarios involving subtle or irregular defect patterns due to their limited capacity for feature abstraction.

In contrast, deep learning models like U-Net, ResNet-50, and YOLOv3 exhibited superior defect detection accuracy, achieving rates as high as 94.5% on high-resolution wafer datasets. Their ability to learn complex spatial hierarchies and context from data significantly enhances their robustness across variable imaging conditions. Despite this, the computational cost remains a critical consideration; inference times for these models ranged between 33.4 and 45.2 milliseconds per image, which could challenge real-time inspection systems unless optimized through model compression or deployment on high-end hardware. As illustrated in Figure 1, a performance-time trade-off becomes apparent—where deep models dominate accuracy but lag in processing speed, while classical techniques remain attractive for latency-sensitive applications. The choice of approach must, therefore, be aligned with the operational constraints of the inspection system, including throughput requirements, hardware availability, and the diversity of defect types encountered in production.

5 Literature Review

The field of wafer defect detection has witnessed a progressive transition from classical image processing techniques to data-driven deep learning models. Early contributions focused predominantly on morphological and statistical image analysis methods. Wu et al. (2014) utilized morphological processing to detect scratch defects, demonstrating effectiveness under controlled imaging conditions but revealing sensitivity to noise and lighting variations. Building on this, Li and Zhang (2016) introduced a Gabor-filter-based feature extraction method coupled with a support vector machine (SVM) classifier, achieving moderate accuracy in distinguishing surface-level defects, especially in grayscale imagery.

The emergence of deep learning significantly advanced the capabilities of automated inspection. Zhang et al. (2018) employed a ResNet-based architecture for classifying defects in semiconductor wafers, achieving substantial improvements in detection accuracy. Their work laid a foundation for leveraging transfer learning and deep feature hierarchies in industrial inspection. Similarly, Liu et al. (2017) applied deep belief networks for anomaly detection in wafer map patterns, showing promise in capturing subtle variations that classical algorithms might overlook.

Hybrid methods have also gained attention. Huang et al. (2020) presented a semi-supervised autoencoder-based system that combines reconstruction errors with edge-detection preprocessing to identify anomalies in unlabeled datasets. Their approach addressed the data scarcity problem while enhancing the interpretability of defect localization. Meanwhile, Tan et al. (2019) proposed an unsupervised deep learning model for surface defect classification, contributing to methods that reduce reliance on extensive labeled datasets.

In parallel, studies such as Park et al. (2015) and Shen et al. (2017) explored PCA and template-matching approaches in classical frameworks. These studies emphasized real-time inspection efficiency, although at the cost of robustness in diverse defect conditions. Complementing these efforts, Wang et al. (2016) adopted random forest classifiers trained on statistical and structural wafer map features, providing a balanced trade-off between interpretability and detection reliability.

Recent investigations shifted focus towards model generalization and scalability. Lee et al. (2018) demonstrated that transfer learning could significantly enhance CNN performance when labeled wafer images were limited. Kim et al. (2019) examined CNN-based classification in photolithography stages, suggesting that model architecture plays a critical role in multi-scale defect recognition. Zhao et al. (2020) further refined this approach by introducing a multi-scale convolutional network capable of detecting small and irregular defects. Comparative performance studies, such as that by Zhou et al. (2018), provided a holistic assessment of both classical and modern methods, highlighting that while deep learning consistently leads in accuracy, classical algorithms remain viable under specific operational constraints.

Together, these studies underscore the evolving landscape of defect detection in wafer inspection—from feature engineering to feature learning—while emphasizing the practical challenges of deploying these models in high-throughput industrial settings.

6 Discussion and Conclusion

Our benchmarking reveals that while deep learning outperforms classical methods in detection accuracy and adaptability, the latter still holds practical value in constrained scenarios. The best solution often involves a hybrid approach, using deep models for training and classical methods for lightweight deployment. Future work should explore transfer learning, domain adaptation, and federated learning to reduce data annotation and improve generalizability across wafer types.

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